



500.38090X00

Applicant: T. WATANABE ET AL.  
Serial No.: 09/462,796  
Filed: January 13, 2000  
For: SEMICONDUCTOR DEVICE, MOUNTING STRUCTURE  
THEREOF AND METHOD OF FABRICATION THEREOF  
Group: 2811  
Examiner: N. Parekh

#14/E  
5/4/02  
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TECHNOLOGY CENTER 2800

AMENDMENT

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

April 29, 2002

Sir:

In response to the Office Action dated January 28, 2002,  
please amend the above-identified application as follows:

In the Claims:

Please amend claims 2-5 and 9-19 as follows:

2. (Amended) A semiconductor device having a plurality of  
pyramidal bump electrodes with a sharp tip, formed of  
conductive materials filling up etched pyramidal holes on a  
base material having a crystal orientation plane, respectively  
bonded through an anisotropic conduction film onto pad  
electrodes arranged on a semiconductor chip.